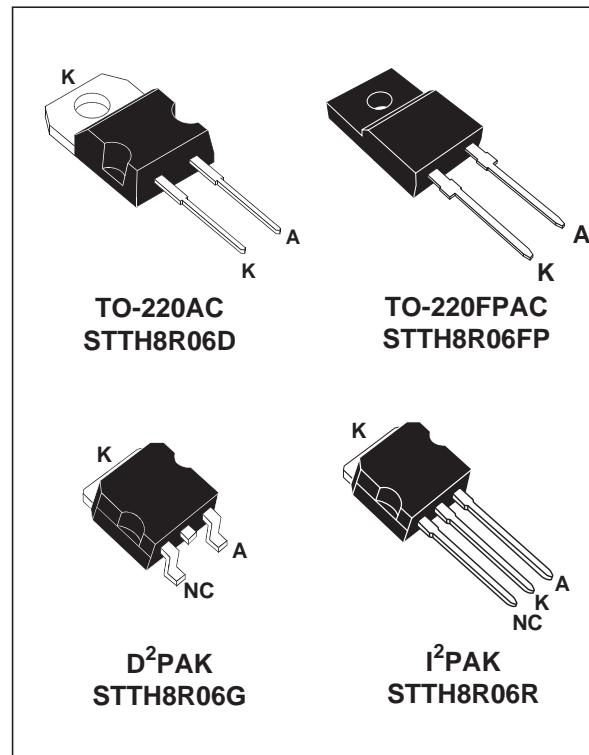


## TURBO 2 ULTRAFAST HIGH VOLTAGE RECTIFIER

### MAIN PRODUCT CHARACTERISTICS

$I_{F(AV)}$	8 A
$V_{RRM}$	600 V
$I_{RM} (\text{typ.})$	5.5A
$T_j (\text{max})$	175 °C
$V_F (\text{max})$	1.8 V
$\text{trr} (\text{max})$	45 ns



### FEATURES AND BENEFITS

- Ultrafast switching
- Low reverse recovery current
- Reduces switching losses
- Low thermal resistance

### DESCRIPTION

The STTH8R06D/FP/G/R, which is using ST 600V technology, is specially suited as boost diode in continuous mode power factor corrections and hard switching conditions.

The device is also intended for use as a free wheeling diode in power supplies and other power switching applications.

### ABSOLUTE RATINGS (limiting values)

Symbol	Parameter		Value	Unit
$V_{RRM}$	Repetitive peak reverse voltage		600	V
$I_{F(\text{RMS})}$	RMS forward current		30	A
$I_{F(AV)}$	Average forward current $\delta = 0.5$	TO-220AC D <sup>2</sup> PAK / I <sup>2</sup> PAK TO-220FPAC	8	A
$I_{FSM}$	Surge non repetitive forward current	$t_p = 10 \text{ ms}$ Sinusoidal	80	A
$T_{\text{stg}}$	Storage temperature range		- 65 + 175	°C
$T_j$	Maximum operating junction temperature		+ 175	°C

## STTH8R06D/FP/G/R

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### THERMAL RESISTANCES

Symbol	Parameter		Value	Unit
$R_{th(j-c)}$	Junction to case	TO-220AC / D <sup>2</sup> PAK / I <sup>2</sup> PAK TO-220FPAC	2.2 4.6	°C/W

### STATIC ELECTRICAL CHARACTERISTICS

Symbol	Parameter	Tests conditions		Min.	Typ.	Max.	Unit
$I_R$	Reverse leakage current	$V_R = 600V$	$T_j = 25°C$			30	$\mu A$
			$T_j = 125°C$		35	400	
$V_F$	Forward voltage drop	$I_F = 8 A$	$T_j = 25°C$			2.9	$V$
			$T_j = 125°C$		1.4	1.8	

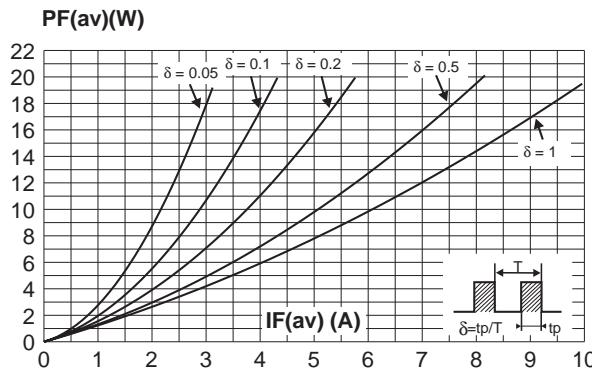
To evaluate the maximum conduction losses use the following equation :

$$P = 1.16 \times I_{F(AV)} + 0.08 I_{F(RMS)}^2$$

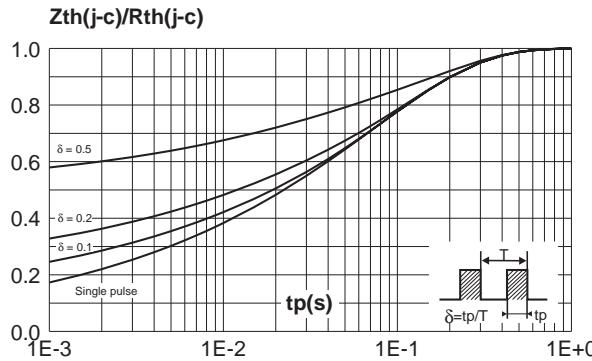
### DYNAMIC ELECTRICAL CHARACTERISTICS

Symbol	Tests conditions		Min.	Typ.	Max.	Unit		
$t_{rr}$	$I_F = 0.5 A$	$I_{rr} = 0.25 A$	$T_j = 25°C$		25	$ns$		
	$I_F = 1 A$	$dI_F/dt = -50 A/\mu s$			45			
$I_{RM}$	$V_R = 400 V$	$I_F = 8A$	$T_j = 125°C$		5.5	7.2	$A$	
S factor					0.3			
$Q_{rr}$					150		$nC$	
$t_{fr}$	$I_F = 8 A$		$T_j = 25°C$		150	$ns$		
$V_{FP}$	$dI_F/dt = 64 A/\mu s$				5	$V$		
	$V_{FR} = 1.1 \times V_{Fmax}$							

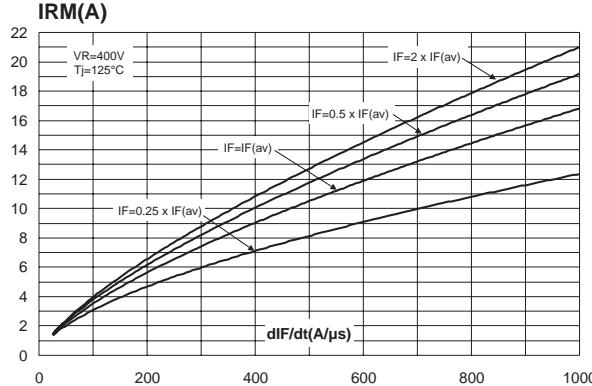
**Fig. 1:** Conduction losses versus average current.



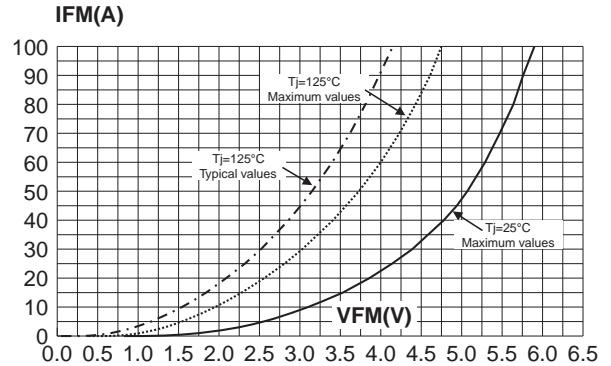
**Fig. 3-1:** Relative variation of thermal impedance junction to case versus pulse duration (TO-220AC, I<sup>2</sup>PAK, D<sup>2</sup>PAK).



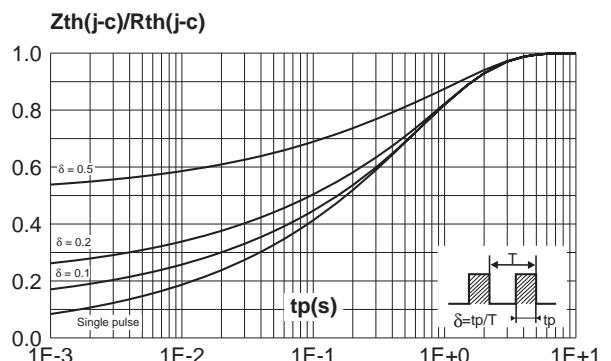
**Fig. 4:** Peak reverse recovery current versus  $dI_F/dt$  (90% confidence).



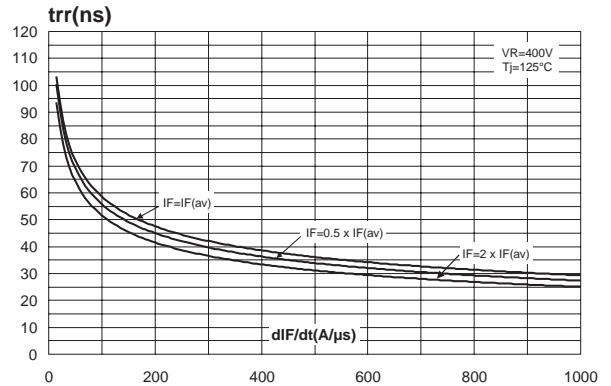
**Fig. 2:** Forward voltage drop versus forward current.



**Fig. 3-2:** Relative variation of thermal impedance junction to case versus pulse duration (TO-220FPAC).

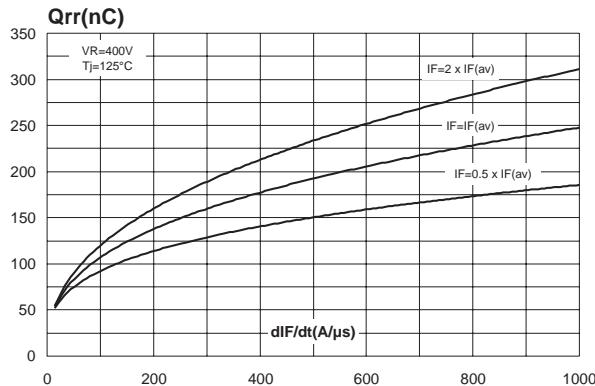


**Fig. 5:** Reverse recovery time versus  $dI_F/dt$  (90% confidence).

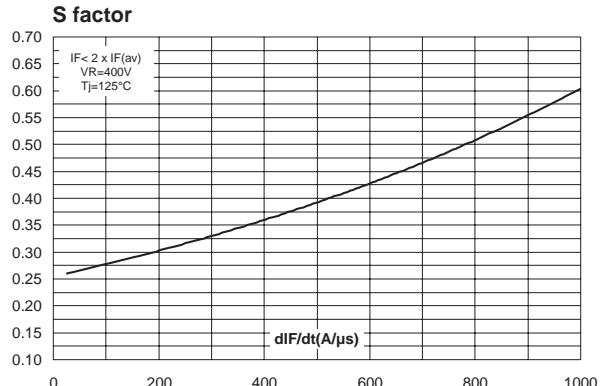


## STTH8R06D/FP/G/R

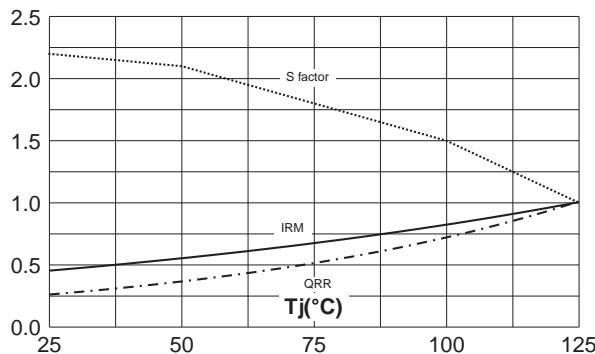
**Fig. 6:** Reverse recovery charges versus  $dI_F/dt$  (90% confidence).



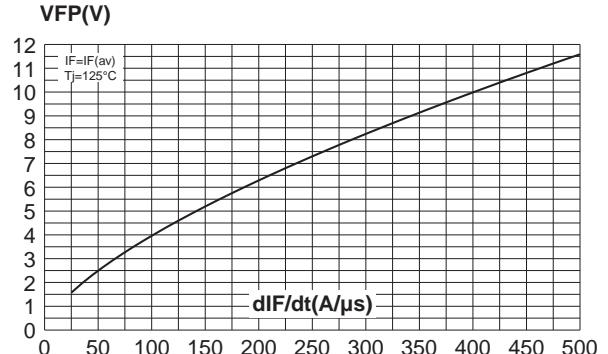
**Fig. 7:** Softness factor (tb/ta) versus  $dI_F/dt$  (typical values).



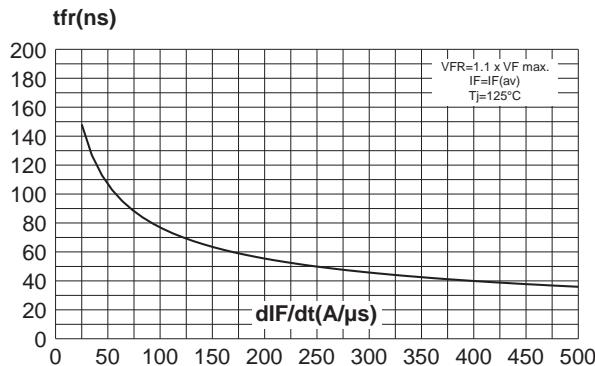
**Fig. 8:** Relative variation of dynamic parameters versus junction temperature (Reference:  $T_j=125^\circ C$ ).



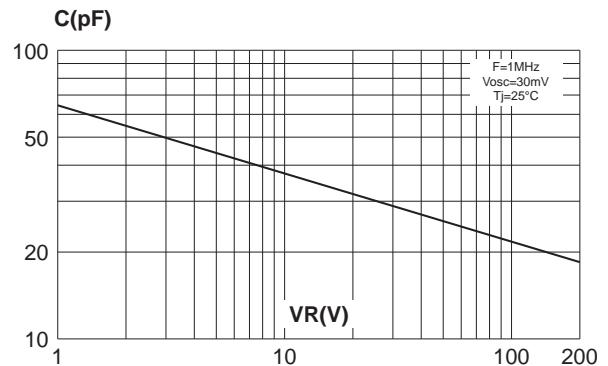
**Fig. 9:** Transient peak forward voltage versus  $dI_F/dt$  (90% confidence).



**Fig. 10:** Forward recovery time versus  $dI_F/dt$  (90% confidence).



**Fig. 11:** Junction capacitance versus reverse voltage applied (typical values).



**PACKAGE MECHANICAL DATA**  
TO-220FPAC

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.4	4.6	0.173	0.181
B	2.5	2.7	0.098	0.106
D	2.5	2.75	0.098	0.108
E	0.45	0.70	0.018	0.027
F	0.75	1	0.030	0.039
F1	1.15	1.70	0.045	0.067
G	4.95	5.20	0.195	0.205
G1	2.4	2.7	0.094	0.106
H	10	10.4	0.393	0.409
L2	16 Typ.		0.63 Typ.	
L3	28.6	30.6	1.126	1.205
L4	9.8	10.6	0.386	0.417
L5	2.9	3.6	0.114	0.142
L6	15.9	16.4	0.626	0.646
L7	9.00	9.30	0.354	0.366
Dia.	3.00	3.20	0.118	0.126

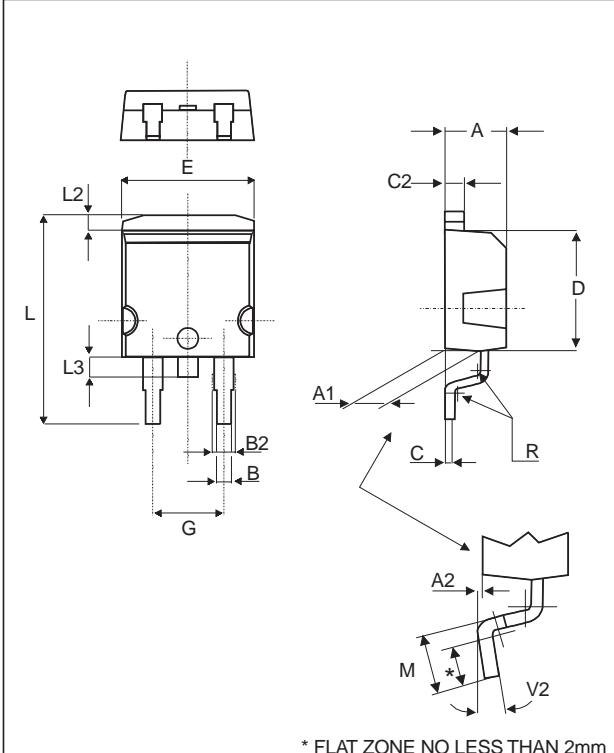
**PACKAGE MECHANICAL DATA**  
TO-220AC

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
C	1.23	1.32	0.048	0.051
D	2.40	2.72	0.094	0.107
E	0.49	0.70	0.019	0.027
F	0.61	0.88	0.024	0.034
F1	1.14	1.70	0.044	0.066
G	4.95	5.15	0.194	0.202
H2	10.00	10.40	0.393	0.409
L2	16.40 typ.		0.645 typ.	
L4	13.00	14.00	0.511	0.551
L5	2.65	2.95	0.104	0.116
L6	15.25	15.75	0.600	0.620
L7	6.20	6.60	0.244	0.259
L9	3.50	3.93	0.137	0.154
M	2.6 typ.		0.102 typ.	
Diam. I	3.75	3.85	0.147	0.151

# STTH8R06D/FP/G/R

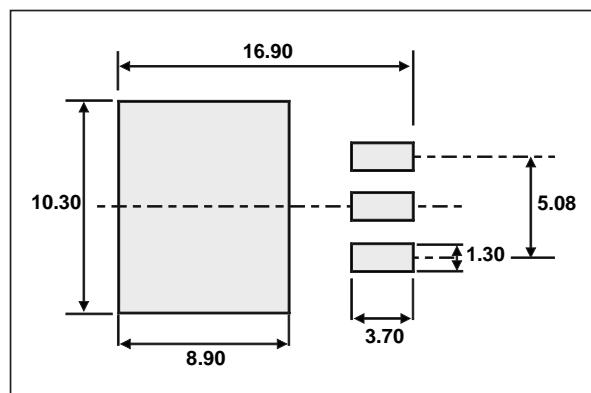
## PACKAGE MECHANICAL DATA

D<sup>2</sup>PAK



REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
A2	0.03	0.23	0.001	0.009
B	0.70	0.93	0.027	0.037
B2	1.14	1.70	0.045	0.067
C	0.45	0.60	0.017	0.024
C2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
E	10.00	10.40	0.393	0.409
G	4.88	5.28	0.192	0.208
L	15.00	15.85	0.590	0.624
L2	1.27	1.40	0.050	0.055
L3	1.40	1.75	0.055	0.069
M	2.40	3.20	0.094	0.126
R	0.40 typ.		0.016 typ.	
V2	0°	8°	0°	8°

## FOOTPRINT (in millimeters)



## STTH8R06D/FP/G/R

### PACKAGE MECHANICAL DATA

I<sup>2</sup>PAK

REF.	DIMENSIONS			
	Millimeters		Inches	
	Min.	Max.	Min.	Max.
A	4.40	4.60	0.173	0.181
A1	2.49	2.69	0.098	0.106
b	0.70	0.93	0.028	0.037
b1	1.14	1.17	0.044	0.046
b2	1.14	1.17	0.044	0.046
c	0.45	0.60	0.018	0.024
c2	1.23	1.36	0.048	0.054
D	8.95	9.35	0.352	0.368
e	2.40	2.70	0.094	0.106
E	10.0	10.4	0.394	0.409
L	13.1	13.6	0.516	0.535
L1	3.48	3.78	0.137	0.149
L2	1.27	1.40	0.050	0.055

Ordering code	Marking	Package	Weight	Base qty	Delivery mode
STTH8R06D	STTH8R06D	TO-220AC	1.9 g	50	Tube
STTH8R06FP	STTH8R06FP	TO-220FPAC	1.7 g	50	Tube
STTH8R06G	STTH8R06G	D <sup>2</sup> PAK	1.5 g	50	Tube
STTH8R06R	STTH8R06R	I <sup>2</sup> PAK	1.5 g	50	Tube

- Cooling method: by conduction (C)
- Recommended torque value (TO-220AC): 0.55 Nm
- Maximum torque value (TO-220AC / TO-220FPAC): 0.7 Nm
- Epoxy meets UL 94,V0

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